Preferred Devices

Dual Series Switching Diodes

The BAV99WT1 is a smaller package, equivalent to the BAV99LT1.

Features

• Pb-Free Packages are Available

Suggested Applications

- ESD Protection
- Polarity Reversal Protection
- Data Line Protection
- Inductive Load Protection
- Steering Logic

MAXIMUM RATINGS (Each Diode)

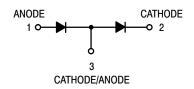
| Rating | Symbol | Value | Unit |
|--|------------------------|-------------------|------|
| Reverse Voltage | V_R | 70 | Vdc |
| Forward Current | I _F | 215 | mAdc |
| Peak Forward Surge Current | I _{FM(surge)} | 500 | mAdc |
| Repetitive Peak Reverse Voltage | V_{RRM} | 70 | V |
| Average Rectified Forward Current (Note 1) (averaged over any 20 ms period) | I _{F(AV)} | 715 | mA |
| Repetitive Peak Forward Current | I _{FRM} | 450 | mA |
| Non-Repetitive Peak Forward Current $t = 1.0 \mu s$ $t = 1.0 ms$ $t = 1.0 S$ | I _{FSM} | 2.0 1.0 0.5 | А |

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

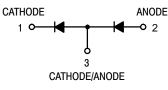
1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.



http://onsemi.com



BAV99WT1 SC-70 CASE 419, STYLE 9



BAV99RWT1 SC-70 CASE 419, STYLE 10

MARKING DIAGRAM SC-70 CASE 419 X7....D

A7 = BAV99WT1 F7 = BAV99RWT1 D = Date Code

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|------------|--------------------|-----------------------|
| BAV99WT1 | SC-70 | 3000/Tape & Reel |
| BAV99WT1G | SC-70 (Pb-Free) | 3000/Tape & Reel |
| BAV99RWT1 | SC-70 | 3000/Tape & Reel |
| BAV99RWT1G | SC-70 (Pb-Free) | 3000/Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

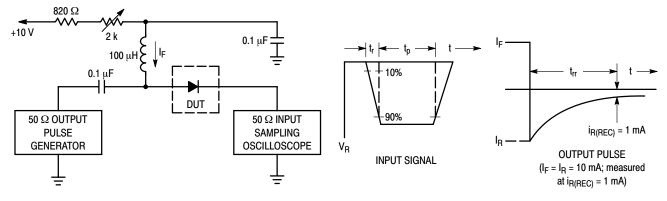
THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|--|-----------------------------------|-------------|-------------|
| Total Device Dissipation FR–5 Board, (Note 1) T _A = 25°C Derate above 25°C | P _D | 200 1.6 | mW mW/°C |
| Thermal Resistance Junction-to-Ambient | $R_{	heta JA}$ | 625 | °C/W |
| Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C | P _D | 300 2.4 | mW mW/°C |
| Thermal Resistance Junction-to-Ambient | $R_{	heta JA}$ | 417 | °C/W |
| Junction and Storage Temperature | T _J , T _{stg} | -65 to +150 | °C |

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (Each Diode)

| Characteristic | Symbol | Min | Max | Unit | |
|--|-------------------|------------------|----------------------------|------|--|
| OFF CHARACTERISTICS | | | | | |
| Reverse Breakdown Voltage (I _(BR) = 100 μA) | V _(BR) | 70 | - | Vdc | |
| Reverse Voltage Leakage Current $(V_R = 70 \text{ Vdc})$ $(V_R = 25 \text{ Vdc}, T_J = 150^{\circ}\text{C})$ $(V_R = 70 \text{ Vdc}, T_J = 150^{\circ}\text{C})$ | I _R | - - - | 2.5 30 50 | μAdc | |
| Diode Capacitance (V _R = 0, f = 1.0 MHz) | C _D | - | 1.5 | pF | |
| Forward Voltage ($I_F = 1.0 \text{ mAdc}$) ($I_F = 10 \text{ mAdc}$) ($I_F = 50 \text{ mAdc}$) ($I_F = 150 \text{ mAdc}$) | V _F | - - - - | 715 855 1000 1250 | mVdc | |
| Reverse Recovery Time (I _F = I _R = 10 mAdc, $i_{R(REC)}$ = 1.0 mAdc) (Figure 1) R_{L} = 100 Ω | t _{rr} | - | 6.0 | ns | |
| Forward Recovery Voltage ($I_F = 10 \text{ mA}, t_r = 20 \text{ ns}$) | V_{FR} | _ | 1.75 | V | |

- 1. FR-5 = $1.0 \times 0.75 \times 0.062$ in. 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.

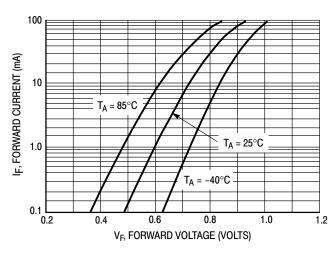


Notes: (a) A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.

- (b) Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.
- (c) t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

CURVES APPLICABLE TO EACH DIODE



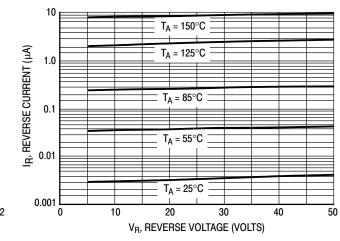


Figure 2. Forward Voltage

Figure 3. Leakage Current

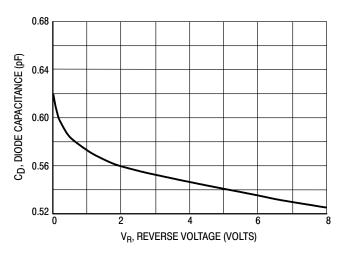
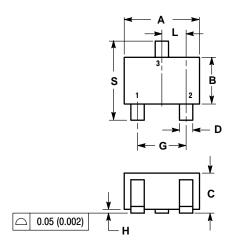
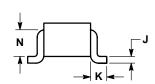


Figure 4. Capacitance

PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 ISSUE L





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- 2. CONTROLLING DIMENSION: INCH.

| | INCHES | | MILLIN | IETERS |
|-----|-----------|-------|-----------|--------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 0.071 | 0.087 | 1.80 | 2.20 |
| В | 0.045 | 0.053 | 1.15 | 1.35 |
| С | 0.032 | 0.040 | 0.80 | 1.00 |
| D | 0.012 | 0.016 | 0.30 | 0.40 |
| G | 0.047 | 0.055 | 1.20 | 1.40 |
| Н | 0.000 | 0.004 | 0.00 | 0.10 |
| J | 0.004 | 0.010 | 0.10 | 0.25 |
| K | 0.017 REF | | 0.425 REF | |
| L | 0.026 BSC | | 0.650 BSC | |
| N | 0.028 REF | | 0.700 REF | |
| S | 0.079 | 0.095 | 2.00 | 2.40 |

STYLE 9: PIN 1. ANODE

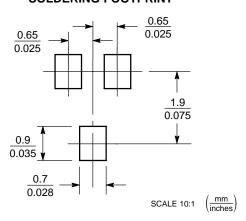
2. CATHODE 3. CATHODE-ANODE

STYLE 10:

PIN 1. CATHODE 2. ANODE

2. ANODE-CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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